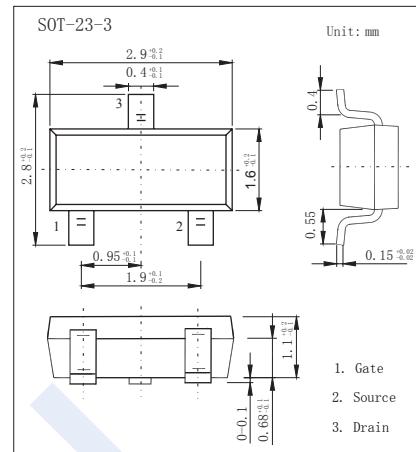
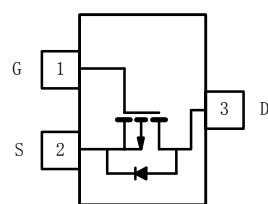


## P-Channel Enhancement MOSFET

## SI2319DS (K12319DS)

## ■ Features

- $V_{DS} (V) = -40V$
- $I_D = -3.0A$  ( $V_{GS} = -10V$ )
- $R_{DS(ON)} < 82m\Omega$  ( $V_{GS} = -10V$ )
- $R_{DS(ON)} < 130m\Omega$  ( $V_{GS} = -4.5V$ )

■ Absolute Maximum Ratings  $T_a = 25^\circ C$ 

| Parameter   | Symbol     | 5 sec          | Steady State | Unit |
|---|------------|----------------|--------------|------|
| Drain-Source Voltage  | $V_{DS}$   | $-40$          | $\pm 20$     | V    |
| Gate-Source Voltage   | $V_{GS}$   |                |              |      |
| Continuous Drain Current $T_a = 25^\circ C$<br>$(T_J = 150^\circ C)^*1$ | $I_D$      | $-3.0$         | $-2.3$       | A    |
| $T_a = 70^\circ C$  |            | $-2.4$         | $-1.85$      |      |
| Pulsed Drain Current  | $I_{DM}$   | $-12$          |              |      |
| Power Dissipation $*1$ $T_a = 25^\circ C$                               | $P_D$      | $1.25$         | $0.75$       | W    |
| $T_a = 70^\circ C$  |            | $0.8$          | $0.48$       |      |
| Thermal Resistance.Junction- to-Ambient $*1$                            | $R_{thJA}$ | $100$          |              | °C/W |
| Thermal Resistance.Junction- to-Ambient $*2$                            |            | $166$          |              |      |
| Thermal Resistance.Junction- to-Foot                                    | $R_{thJF}$ | $50$           |              |      |
| Junction Temperature  | $T_J$      | $150$          |              | °C   |
| Storage Temperature Range   | $T_{stg}$  | $-55$ to $150$ |              |      |

\*1 Surface Mounted on FR4 Board,  $t \leqslant 5$  sec.

\*2 Surface Mounted on FR4 Board.

## P-Channel Enhancement MOSFET

### SI2319DS (K12319DS)

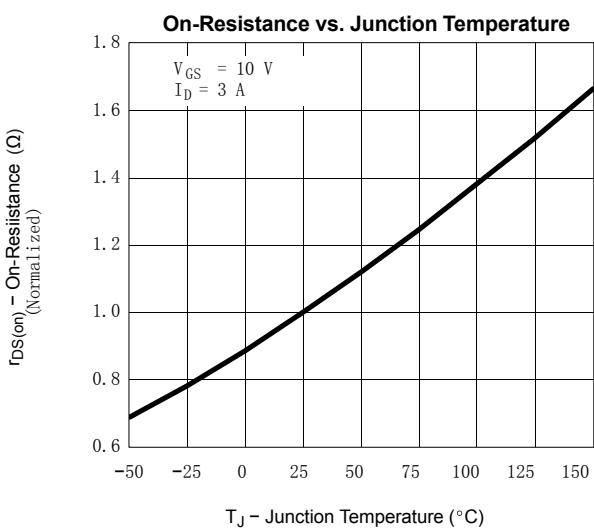
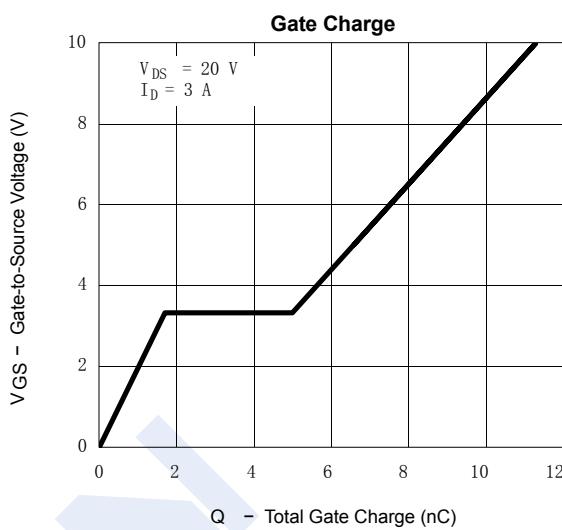
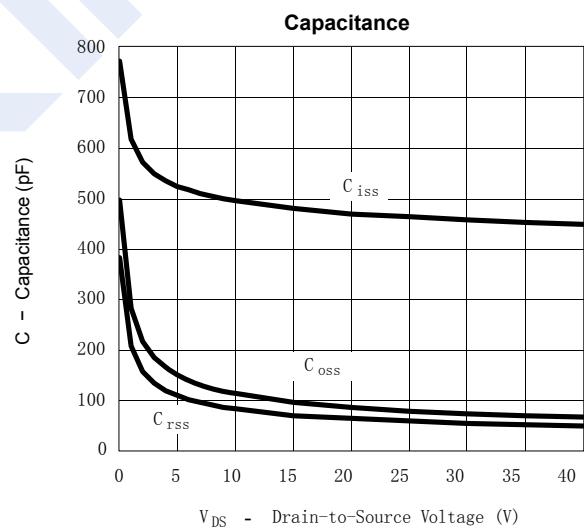
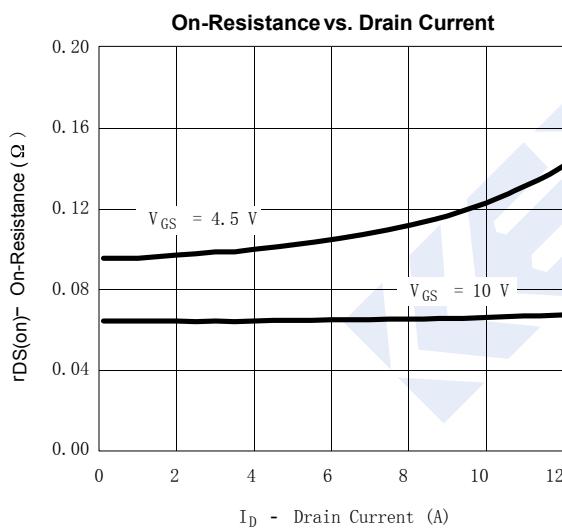
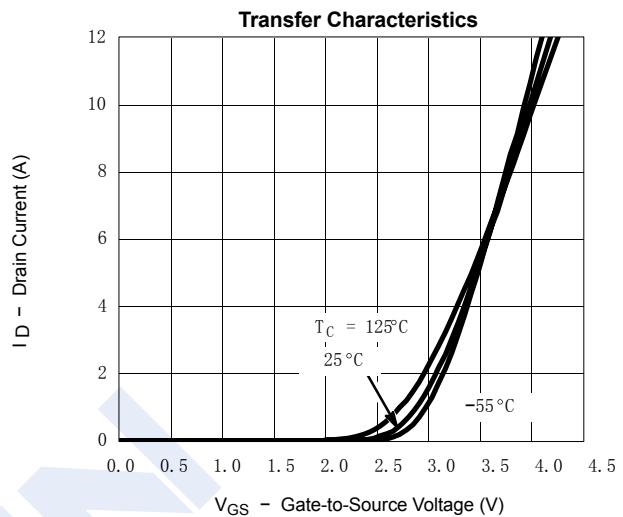
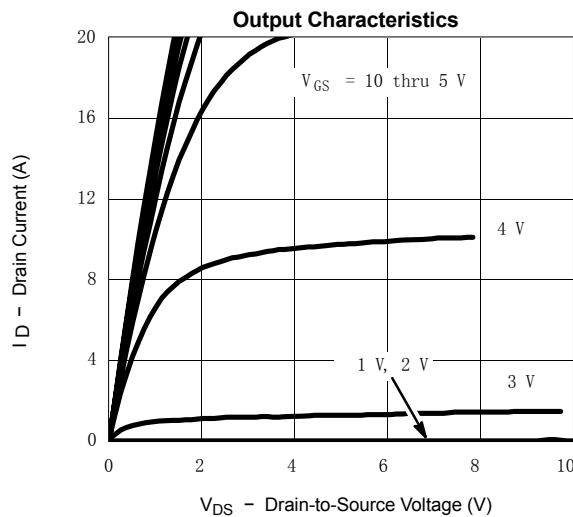
■ Electrical Characteristics  $T_a = 25^\circ\text{C}$

| Parameter                             | Symbol       | Test Conditions  | Min | Typ  | Max       | Unit             |
|---------------------------------------|--------------|--|-----|------|-----------|------------------|
| Drain-Source Breakdown Voltage        | $V_{DSS}$    | $I_D=-250 \mu\text{A}, V_{GS}=0\text{V}$   | -40 |      |           | V                |
| Zero Gate Voltage Drain Current       | $I_{DSS}$    | $V_{DS}=-40\text{V}, V_{GS}=0\text{V}$   |     |      | -1        | $\mu\text{A}$    |
|                                       |              | $V_{DS}=-40\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$                                     |     |      | -10       |                  |
| Gate-Body leakage current             | $I_{GSS}$    | $V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$  |     |      | $\pm 100$ | nA               |
| Gate Threshold Voltage                | $V_{GS(th)}$ | $V_{DS}=V_{GS} I_D=-250 \mu\text{A}$   | -1  |      | -3        | V                |
| Static Drain-Source On-Resistance *1  | $R_{DS(on)}$ | $V_{GS}=-10\text{V}, I_D=-3.0\text{A}$   |     | 65   | 82        | $\text{m}\Omega$ |
|                                       |              | $V_{GS}=-4.5\text{V}, I_D=-2.4\text{A}$  |     | 100  | 130       |                  |
| On state drain current *1             | $I_{D(ON)}$  | $V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$  | -6  |      |           | A                |
| Forward Transconductance *1           | $g_{FS}$     | $V_{DS}=-5\text{V}, I_D=-3.0\text{A}$  |     | 7    |           | S                |
| Input Capacitance                     | $C_{iss}$    | $V_{GS}=0\text{V}, V_{DS}=-20\text{V}, f=1\text{MHz}$  |     | 470  |           | $\text{pF}$      |
| Output Capacitance                    | $C_{oss}$    |  |     | 85   |           |                  |
| Reverse Transfer Capacitance          | $C_{rss}$    |  |     | 65   |           |                  |
| Total Gate Charge                     | $Q_g$        | $V_{GS}=-10\text{V}, V_{DS}=-20\text{V}, I_D=-3\text{A}$   |     | 11.3 | 17        | $\text{nC}$      |
| Gate Source Charge                    | $Q_{gs}$     |  |     | 1.7  |           |                  |
| Gate Drain Charge                     | $Q_{gd}$     |  |     | 3.3  |           |                  |
| Turn-On DelayTime                     | $t_{d(on)}$  | $V_{GS}=-4.5\text{V}, V_{DS}=-20\text{V}, R_L=20 \Omega, R_{GEN}=6 \Omega$<br>$I_D=-1.0\text{A}$ |     | 7    | 15        | $\text{ns}$      |
| Turn-On Rise Time                     | $t_r$        |  |     | 15   | 25        |                  |
| Turn-Off DelayTime                    | $t_{d(off)}$ |  |     | 25   | 40        |                  |
| Turn-Off Fall Time                    | $t_f$        |  |     | 25   | 40        |                  |
| Maximum Body-Diode Continuous Current | $I_s$        |  |     |      | -1.25     | A                |
| Diode Forward Voltage                 | $V_{SD}$     | $I_s=-1.25 \text{ A}, V_{GS}=0\text{V}$  |     | -0.8 | -1.2      | V                |

\*1Pulse test: PW  $\leqslant 300\text{us}$  duty cycle  $\leqslant 2\%$ .

■ Marking

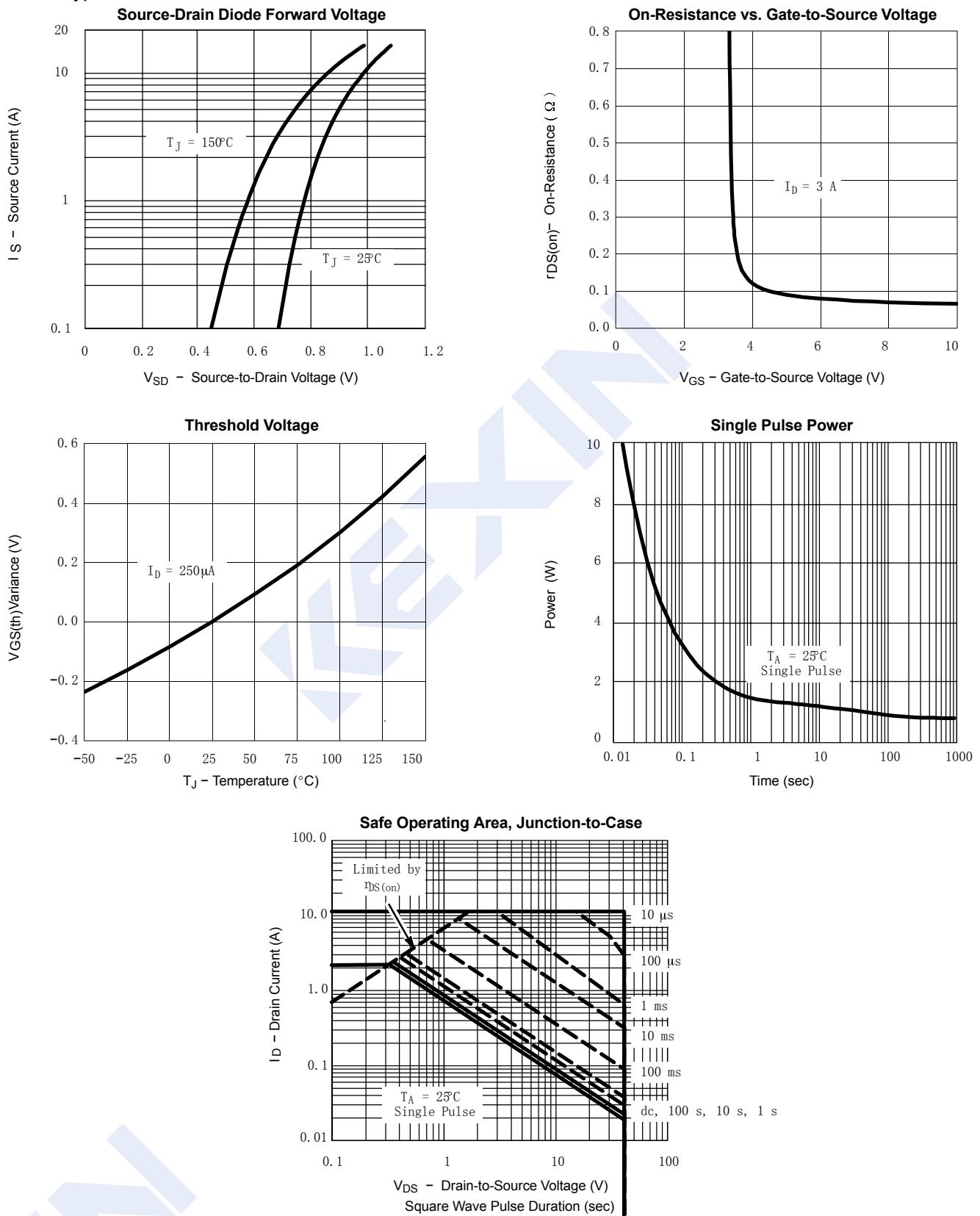
|         |     |
|---------|-----|
| Marking | C9* |
|---------|-----|

**P-Channel Enhancement MOSFET****SI2319DS (K12319DS)****■ Typical Characteristics**

## P-Channel Enhancement MOSFET

### SI2319DS (K2319DS)

#### ■ Typical Characteristics



## P-Channel Enhancement MOSFET

### SI2319DS (K12319DS)

#### ■ Typical Characteristics

